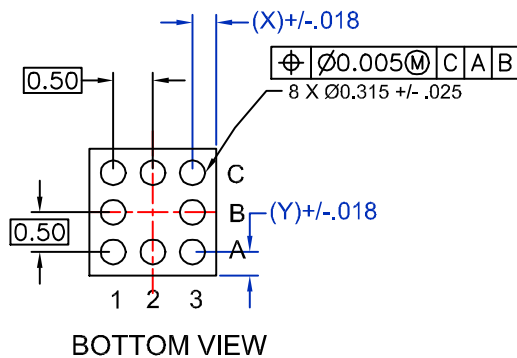
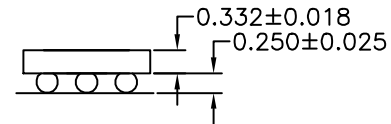
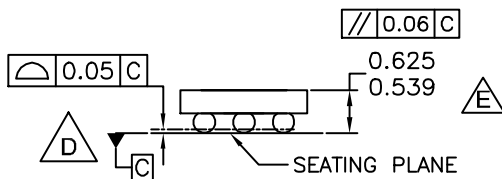
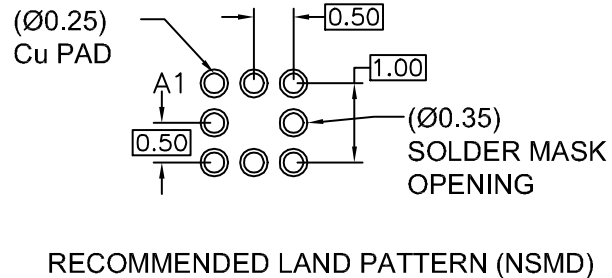
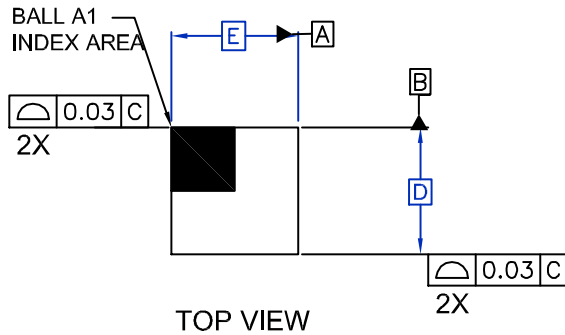


WLCSP8 1.57x1.57x0.582
CASE 567PZ
ISSUE O

DATE 31 OCT 2016



NOTES:

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994
- D. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
- E. PACKAGE TYPICAL HEIGHT IS 582 MICRONS ± 43 MICRONS (539-625 MICRONS).
- F. FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.
- G. BALL COMPOSITION: Sn95.5-Ag3.9-Cu0.6

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DESCRIPTION:	WLCSP8 1.57x1.57x0.582	PAGE 1 OF 1

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